

MATERIAL DECLARATION SHEET



Material Number	ESD Suppressing Device CDDFN2-T3.3B			
Product Line	Semiconductor Products			
Compliance Date	2013/8/2			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.0357	Silicon	7440-21-3	100.00%	3.854%	3.854%
2	Lead frame	Copper Alloy (NiPdAu)	0.4125	Copper	7440-50-8	93.9971%	44.534%	47.386%
			0.0023	Silicon	7440-21-3	0.5196%	0.248%	
			0.0151	Nickel	7440-02-0	3.4298%	1.630%	
			0.0006	Magnesium	7439-95-4	0.1345%	0.065%	
			0.0004	Iron	7439-89-6	0.1003%	0.043%	
			0.0022	Zinc	7440-66-6	0.4991%	0.238%	
			0.0002	Manganese	7439-96-5	0.0501%	0.022%	
			0.00001	Lead	7439-92-1	0.0023%	0.001%	
		Nickel plating	0.0051	Nickel	7440-02-0	1.1509%	0.551%	
		Pd plating	0.0004	Palladium	7440-05-3	0.1003%	0.043%	
		Au plating	0.0001	Gold	7440-57-5	0.0160%	0.011%	

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3	Epoxy	Polymer	0.006	Silver	7440-22-4	80.50%	0.648%	0.826%
			0.001	Carbocyclic Acrylates	proprietary	10.00%	0.108%	
			0.0002	Bismaleimide resin	proprietary	3.00%	0.022%	
			0.0002	2-preponoic acid, 2-methyl	68586-19-6	3.00%	0.022%	
			0.0002	Additive, not to declare	proprietary	3.00%	0.022%	
			0.00004	Dicumyl peroxide	80-43-3	0.50%	0.004%	
4	Wire	Noble metal	0.0049	Gold	7440-57-5	99.99%	0.529%	0.54%
			0.0001	Other, not to declare	/	0.01%	0.011%	
5	Mold Compound	Polymer	0.412	Silica Fused	60676-86-0	93.70%	44.478%	47.394%
			0.013	Epoxy Resin	Proprietary	3.00%	1.404%	
			0.013	Phenol Resin	Proprietary	3.00%	1.404%	
			0.001	Carbon Black	1333-86-4	0.30%	0.108%	
		Total weight	0.92625mg					

This Document was updated on: 2015/01/13

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.